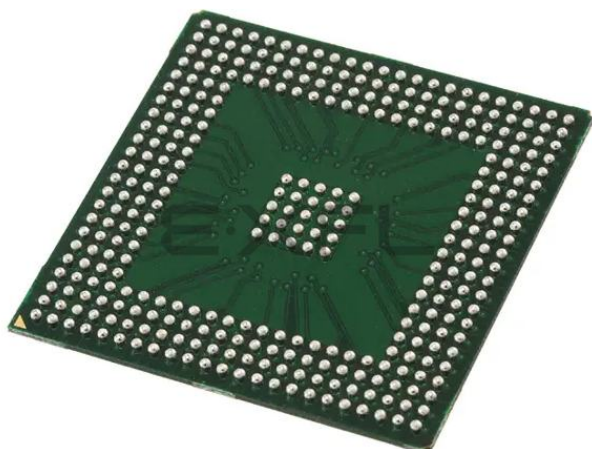




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	2880
Number of Logic Elements/Cells	-
Total RAM Bits	-
Number of I/O	249
Number of Gates	48000
Voltage - Supply	2.25V ~ 5.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	329-BBGA
Supplier Device Package	329-PBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a54sx32a-1bg329i

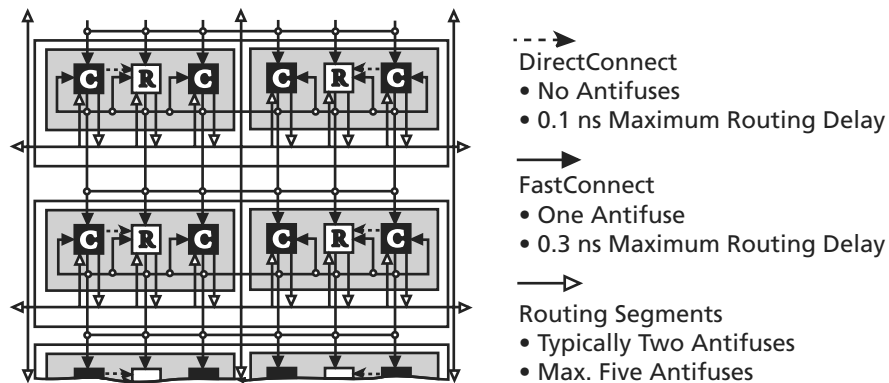


Figure 1-5 • DirectConnect and FastConnect for Type 1 SuperClusters

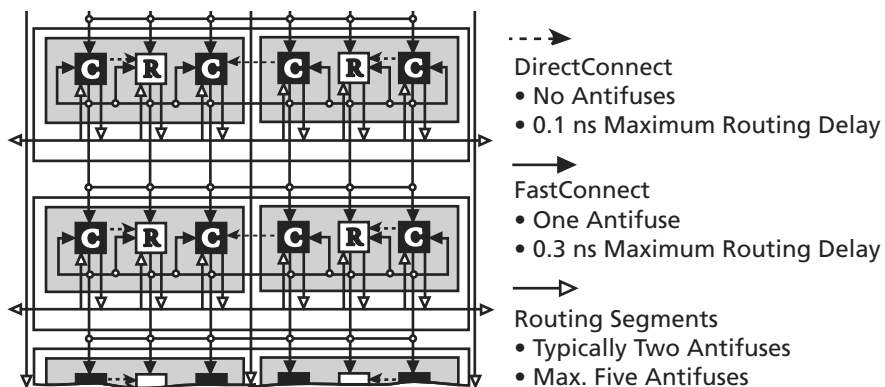


Figure 1-6 • DirectConnect and FastConnect for Type 2 SuperClusters

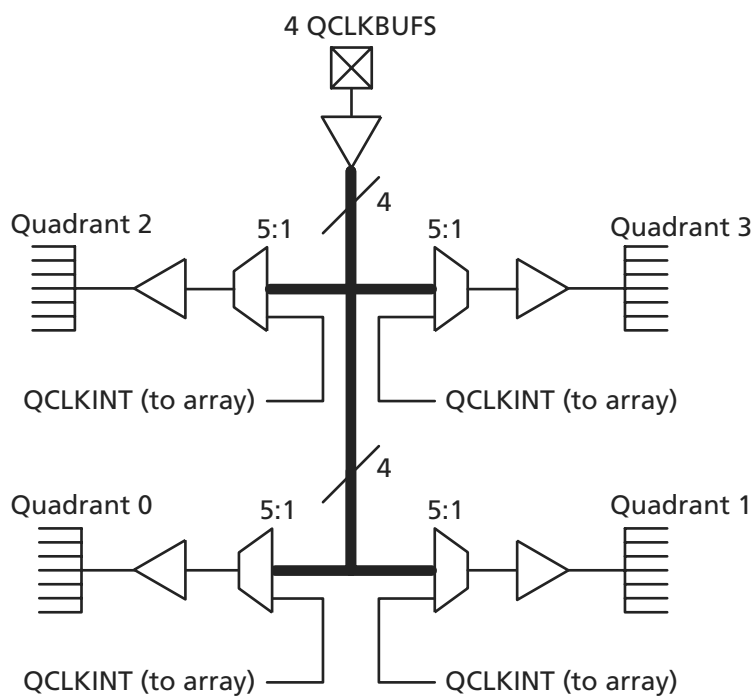


Figure 1-9 • SX-A QCLK Architecture

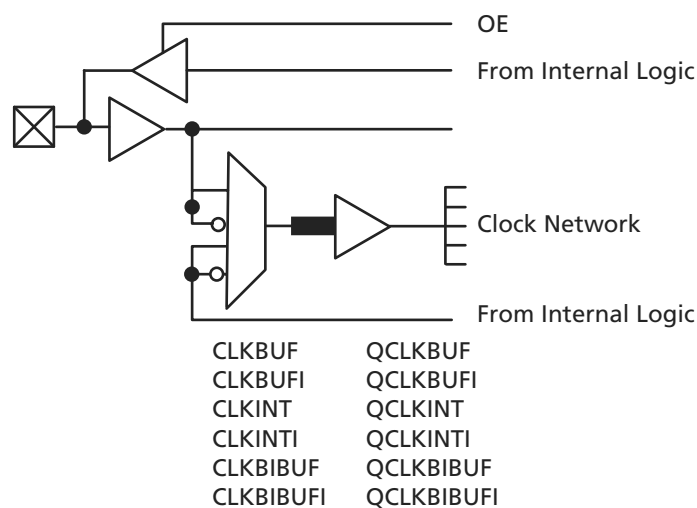


Figure 1-10 • A54SX72A Routed Clock and QCLK Buffer

Probing Capabilities

SX-A devices also provide an internal probing capability that is accessed with the JTAG pins. The Silicon Explorer II diagnostic hardware is used to control the TDI, TCK, TMS, and TDO pins to select the desired nets for debugging. The user assigns the selected internal nets in Actel Silicon Explorer II software to the PRA/PRB output pins for observation. Silicon Explorer II automatically places the device into JTAG mode. However, probing functionality is only activated when the TRST pin is driven high or left floating, allowing the internal pull-up resistor to pull TRST High. If the TRST pin is held Low, the TAP controller remains in the Test-Logic-Reset state so no probing can be performed. However, the user must drive the TRST pin High or allow the internal pull-up resistor to pull TRST High.

When selecting the **Reserve Probe Pin** box as shown in Figure 1-12 on page 1-9, direct the layout tool to reserve the PRA and PRB pins as dedicated outputs for probing. This **Reserve** option is merely a guideline. If the designer assigns user I/Os to the PRA and PRB pins and selects the **Reserve Probe Pin** option, Designer Layout will override the **Reserve Probe Pin** option and place the user I/Os on those pins.

To allow probing capabilities, the security fuse must not be programmed. Programming the security fuse disables the JTAG and probe circuitry. Table 1-9 summarizes the possible device configurations for probing once the device leaves the Test-Logic-Reset JTAG state.

Table 1-9 • Device Configuration Options for Probe Capability (TRST Pin Reserved)

JTAG Mode	TRST ¹	Security Fuse Programmed	PRA, PRB ²	TDI, TCK, TDO ²
Dedicated	Low	No	User I/O ³	JTAG Disabled
	High	No	Probe Circuit Outputs	JTAG I/O
Flexible	Low	No	User I/O ³	User I/O ³
	High	No	Probe Circuit Outputs	JTAG I/O
		Yes	Probe Circuit Secured	Probe Circuit Secured

Notes:

1. If the TRST pin is not reserved, the device behaves according to TRST = High as described in the table.
2. Avoid using the TDI, TCK, TDO, PRA, and PRB pins as input or bidirectional ports. Since these pins are active during probing, input signals will not pass through these pins and may cause contention.
3. If no user signal is assigned to these pins, they will behave as unused I/Os in this mode. Unused pins are automatically tristated by the Designer software.

Figure 2-1 shows the 5 V PCI V/I curve and the minimum and maximum PCI drive characteristics of the SX-A family.

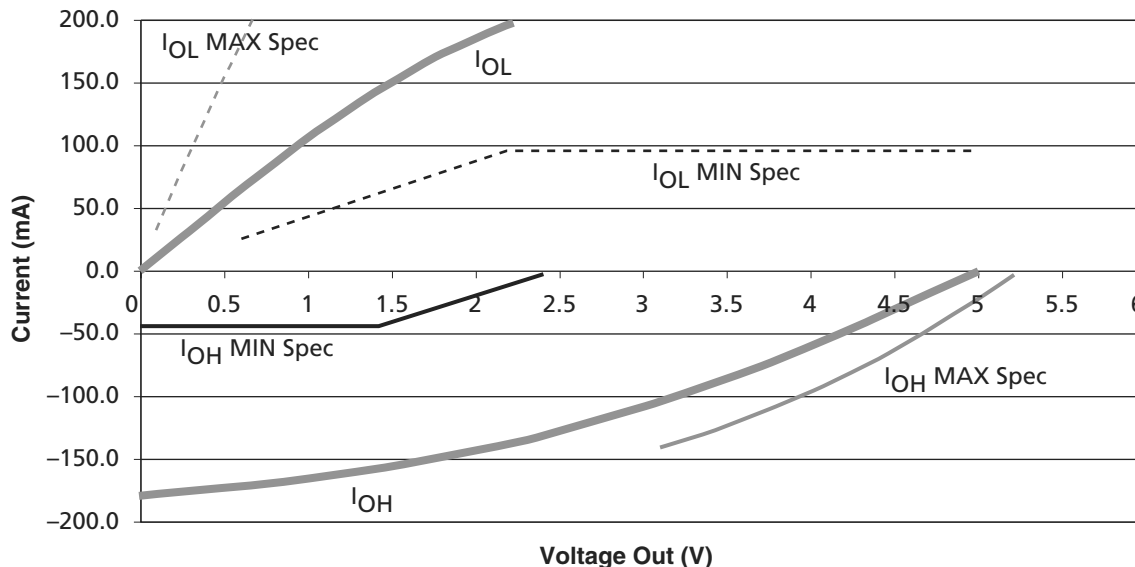


Figure 2-1 • 5 V PCI V/I Curve for SX-A Family

$$I_{OH} = 11.9 * (V_{OUT} - 5.25) * (V_{OUT} + 2.45)$$

for $V_{CCI} > V_{OUT} > 3.1V$

EQ 2-1

$$I_{OL} = 78.5 * V_{OUT} * (4.4 - V_{OUT})$$

for $0V < V_{OUT} < 0.71V$

EQ 2-2

Table 2-9 • DC Specifications (3.3 V PCI Operation)

Symbol	Parameter	Condition	Min.	Max.	Units
V_{CCA}	Supply Voltage for Array		2.25	2.75	V
V_{CCI}	Supply Voltage for I/Os		3.0	3.6	V
V_{IH}	Input High Voltage		$0.5V_{CCI}$	$V_{CCI} + 0.5$	V
V_{IL}	Input Low Voltage		-0.5	$0.3V_{CCI}$	V
I_{IPU}	Input Pull-up Voltage ¹		$0.7V_{CCI}$	–	V
I_{IL}	Input Leakage Current ²	$0 < V_{IN} < V_{CCI}$	-10	+10	μA
V_{OH}	Output High Voltage	$I_{OUT} = -500 \mu A$	$0.9V_{CCI}$	–	V
V_{OL}	Output Low Voltage	$I_{OUT} = 1,500 \mu A$		$0.1V_{CCI}$	V
C_{IN}	Input Pin Capacitance ³		–	10	pF
C_{CLK}	CLK Pin Capacitance		5	12	pF

Notes:

1. This specification should be guaranteed by design. It is the minimum voltage to which pull-up resistors are calculated to pull a floated network. Designers should ensure that the input buffer is conducting minimum current at this input voltage in applications sensitive to static power utilization.
2. Input leakage currents include hi-Z output leakage for all bidirectional buffers with tristate outputs.
3. Absolute maximum pin capacitance for a PCI input is 10 pF (except for CLK).

Where:

- C_{EQCM} = Equivalent capacitance of combinatorial modules (C-cells) in pF
 C_{EQSM} = Equivalent capacitance of sequential modules (R-Cells) in pF
 C_{EQI} = Equivalent capacitance of input buffers in pF
 C_{EQO} = Equivalent capacitance of output buffers in pF
 C_{EQCR} = Equivalent capacitance of CLKA/B in pF
 C_{EQHV} = Variable capacitance of HCLK in pF
 C_{EQHF} = Fixed capacitance of HCLK in pF
 C_L = Output lead capacitance in pF
 f_m = Average logic module switching rate in MHz
 f_n = Average input buffer switching rate in MHz
 f_p = Average output buffer switching rate in MHz
 f_{q1} = Average CLKA rate in MHz
 f_{q2} = Average CLKB rate in MHz
 f_{s1} = Average HCLK rate in MHz
 m = Number of logic modules switching at f_m
 n = Number of input buffers switching at f_n
 p = Number of output buffers switching at f_p
 q_1 = Number of clock loads on CLKA
 q_2 = Number of clock loads on CLKB
 r_1 = Fixed capacitance due to CLKA
 r_2 = Fixed capacitance due to CLKB
 s_1 = Number of clock loads on HCLK
 x = Number of I/Os at logic low
 y = Number of I/Os at logic high

Table 2-11 • CEQ Values for SX-A Devices

	A54SX08A	A54SX16A	A54SX32A	A54SX72A
Combinatorial modules (C_{EQCM})	1.70 pF	2.00 pF	2.00 pF	1.80 pF
Sequential modules (C_{EQSM})	1.50 pF	1.50 pF	1.30 pF	1.50 pF
Input buffers (C_{EQI})	1.30 pF	1.30 pF	1.30 pF	1.30 pF
Output buffers (C_{EQO})	7.40 pF	7.40 pF	7.40 pF	7.40 pF
Routed array clocks (C_{EQCR})	1.05 pF	1.05 pF	1.05 pF	1.05 pF
Dedicated array clocks – variable (C_{EQHV})	0.85 pF	0.85 pF	0.85 pF	0.85 pF
Dedicated array clocks – fixed (C_{EQHF})	30.00 pF	55.00 pF	110.00 pF	240.00 pF
Routed array clock A (r_1)	35.00 pF	50.00 pF	90.00 pF	310.00 pF

To determine the heat sink's thermal performance, use the following equation:

$$\theta_{JA(TOTAL)} = \theta_{JC} + \theta_{CS} + \theta_{SA}$$

EQ 2-14

where:

$$\theta_{CS} = 0.37^{\circ}\text{C/W}$$

= thermal resistance of the interface material between the case and the heat sink, usually provided by the thermal interface manufacturer

$$\theta_{SA} = \text{thermal resistance of the heat sink in } ^{\circ}\text{C/W}$$

$$\theta_{SA} = \theta_{JA(TOTAL)} - \theta_{JC} - \theta_{CS}$$

EQ 2-15

$$\theta_{SA} = 13.33^{\circ}\text{C/W} - 3.20^{\circ}\text{C/W} - 0.37^{\circ}\text{C/W}$$

$$\theta_{SA} = 9.76^{\circ}\text{C/W}$$

A heat sink with a thermal resistance of 9.76°C/W or better should be used. Thermal resistance of heat sinks is a function of airflow. The heat sink performance can be significantly improved with the presence of airflow.

Carefully estimating thermal resistance is important in the long-term reliability of an Actel FPGA. Design engineers should always correlate the power consumption of the device with the maximum allowable power dissipation of the package selected for that device, using the provided thermal resistance data.

Note: The values may vary depending on the application.

Table 2-18 • A54SX08A Timing Characteristics

(Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 2.3\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	–2 Speed		–1 Speed		Std. Speed		–F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
2.5 V LVCMOS Output Module Timing ^{1,2}										
t _{DLH}	Data-to-Pad Low to High		3.9		4.4		5.2		7.2	ns
t _{DHL}	Data-to-Pad High to Low		3.0		3.4		3.9		5.5	ns
t _{DHLS}	Data-to-Pad High to Low—low slew		13.3		15.1		17.7		24.8	ns
t _{ENZL}	Enable-to-Pad, Z to L		2.8		3.2		3.7		5.2	ns
t _{ENZLS}	Data-to-Pad, Z to L—low slew		13.7		15.5		18.2		25.5	ns
t _{ENZH}	Enable-to-Pad, Z to H		3.9		4.4		5.2		7.2	ns
t _{ENLZ}	Enable-to-Pad, L to Z		2.5		2.8		3.3		4.7	ns
t _{ENHZ}	Enable-to-Pad, H to Z		3.0		3.4		3.9		5.5	ns
d _{TLH} ³	Delta Low to High		0.037		0.043		0.051		0.071	ns/pF
d _{THL} ³	Delta High to Low		0.017		0.023		0.023		0.037	ns/pF
d _{THLS} ³	Delta High to Low—low slew		0.06		0.071		0.086		0.117	ns/pF

Note:

- Delays based on 35 pF loading.
- The equivalent I/O Attribute Editor settings for 2.5 V LVCMOS is 2.5 V LVTTTL in the software.
- To obtain the slew rate, substitute the appropriate Delta value, load capacitance, and the V_{CCI} value into the following equation:

$$\text{Slew Rate [V/ns]} = (0.1 * V_{CCI} - 0.9 * V_{CCI}) / (C_{load} * d_{T[HL|HL|HLS]})$$
where C_{load} is the load capacitance driven by the I/O in pF
 $d_{T[HL|HL|HLS]}$ is the worst case delta value from the datasheet in ns/pF.

Table 2-19 • A54SX08A Timing Characteristics
(Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	–2 Speed		–1 Speed		Std. Speed		–F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
3.3 V PCI Output Module Timing ¹										
t _{DLH}	Data-to-Pad Low to High	2.2		2.4		2.9		4.0		ns
t _{DHL}	Data-to-Pad High to Low	2.3		2.6		3.1		4.3		ns
t _{ENZL}	Enable-to-Pad, Z to L	1.7		1.9		2.2		3.1		ns
t _{ENZH}	Enable-to-Pad, Z to H	2.2		2.4		2.9		4.0		ns
t _{ENLZ}	Enable-to-Pad, L to Z	2.8		3.2		3.8		5.3		ns
t _{ENHZ}	Enable-to-Pad, H to Z	2.3		2.6		3.1		4.3		ns
d _{TLH} ²	Delta Low to High	0.03		0.03		0.04		0.045		ns/pF
d _{THL} ²	Delta High to Low	0.015		0.015		0.015		0.025		ns/pF
3.3 V LVTTTL Output Module Timing ³										
t _{DLH}	Data-to-Pad Low to High	3.0		3.4		4.0		5.6		ns
t _{DHL}	Data-to-Pad High to Low	3.0		3.3		3.9		5.5		ns
t _{DHLS}	Data-to-Pad High to Low—low slew	10.4		11.8		13.8		19.3		ns
t _{ENZL}	Enable-to-Pad, Z to L	2.6		2.9		3.4		4.8		ns
t _{ENZLS}	Enable-to-Pad, Z to L—low slew	18.9		21.3		25.4		34.9		ns
t _{ENZH}	Enable-to-Pad, Z to H	3		3.4		4		5.6		ns
t _{ENLZ}	Enable-to-Pad, L to Z	3.3		3.7		4.4		6.2		ns
t _{ENHZ}	Enable-to-Pad, H to Z	3		3.3		3.9		5.5		ns
d _{TLH} ²	Delta Low to High	0.03		0.03		0.04		0.045		ns/pF
d _{THL} ²	Delta High to Low	0.015		0.015		0.015		0.025		ns/pF
d _{THLS} ²	Delta High to Low—low slew	0.053		0.067		0.073		0.107		ns/pF

Notes:

- Delays based on 10 pF loading and 25 Ω resistance.
- To obtain the slew rate, substitute the appropriate Delta value, load capacitance, and the V_{CCI} value into the following equation:

$$\text{Slew Rate [V/ns]} = (0.1 * V_{CCI} - 0.9 * V_{CCI}) / (C_{load} * d_{T[HL|HL|HLS]})$$
 where C_{load} is the load capacitance driven by the I/O in pF
 $d_{T[HL|HL|HLS]}$ is the worst case delta value from the datasheet in ns/pF.
- Delays based on 35 pF loading.

Table 2-28 • A54SX32A Timing Characteristics (Continued)
(Worst-Case Commercial Conditions, $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed ¹		-2 Speed		-1 Speed		Std. Speed		-F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{INYH}	Input Data Pad to Y High 5 V PCI		0.7		0.8		0.9		1.0		1.4	ns
t_{INYL}	Input Data Pad to Y Low 5 V PCI		0.9		1.1		1.2		1.4		1.9	ns
t_{INYH}	Input Data Pad to Y High 5 V TTL		0.9		1.1		1.2		1.4		1.9	ns
t_{INYL}	Input Data Pad to Y Low 5 V TTL		1.4		1.6		1.8		2.1		2.9	ns
Input Module Predicted Routing Delays³												
t_{IRD1}	FO = 1 Routing Delay		0.3		0.3		0.3		0.4		0.6	ns
t_{IRD2}	FO = 2 Routing Delay		0.4		0.5		0.5		0.6		0.8	ns
t_{IRD3}	FO = 3 Routing Delay		0.5		0.6		0.7		0.8		1.1	ns
t_{IRD4}	FO = 4 Routing Delay		0.7		0.8		0.9		1		1.4	ns
t_{IRD8}	FO = 8 Routing Delay		1.2		1.4		1.5		1.8		2.5	ns
t_{IRD12}	FO = 12 Routing Delay		1.7		2		2.2		2.6		3.6	ns

Notes:

1. All -3 speed grades have been discontinued.
2. For dual-module macros, use $t_{PD} + t_{RD1} + t_{PDn}$, $t_{RCO} + t_{RD1} + t_{PDn}$, or $t_{PD1} + t_{RD1} + t_{SUD}$, whichever is appropriate.
3. Routing delays are for typical designs across worst-case operating conditions. These parameters should be used for estimating device performance. Post-route timing analysis or simulation is required to determine actual performance.

Table 2-37 • A54SX72A Timing Characteristics (Continued)
(Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	–3 Speed*		–2 Speed		–1 Speed		Std. Speed		–F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{QCKH}	Input Low to High (100% Load) (Pad to R-cell Input)		1.7		1.9		2.2		2.5		3.5	ns
t_{QCHKL}	Input High to Low (100% Load) (Pad to R-cell Input)		1.7		2		2.2		2.6		3.6	ns
t_{QPWH}	Minimum Pulse Width High	1.5		1.7		2.0		2.3		3.2		ns
t_{QPWL}	Minimum Pulse Width Low	1.5		1.7		2.0		2.3		3.2		ns
t_{QCKSW}	Maximum Skew (Light Load)		0.2		0.3		0.3		0.3		0.5	ns
t_{QCKSW}	Maximum Skew (50% Load)		0.4		0.5		0.5		0.6		0.9	ns
t_{QCKSW}	Maximum Skew (100% Load)		0.4		0.5		0.5		0.6		0.9	ns

Note: *All –3 speed grades have been discontinued.

144-Pin TQFP			
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function
1	GND	GND	GND
2	TDI, I/O	TDI, I/O	TDI, I/O
3	I/O	I/O	I/O
4	I/O	I/O	I/O
5	I/O	I/O	I/O
6	I/O	I/O	I/O
7	I/O	I/O	I/O
8	I/O	I/O	I/O
9	TMS	TMS	TMS
10	V _{CCI}	V _{CCI}	V _{CCI}
11	GND	GND	GND
12	I/O	I/O	I/O
13	I/O	I/O	I/O
14	I/O	I/O	I/O
15	I/O	I/O	I/O
16	I/O	I/O	I/O
17	I/O	I/O	I/O
18	I/O	I/O	I/O
19	NC	NC	NC
20	V _{CCA}	V _{CCA}	V _{CCA}
21	I/O	I/O	I/O
22	TRST, I/O	TRST, I/O	TRST, I/O
23	I/O	I/O	I/O
24	I/O	I/O	I/O
25	I/O	I/O	I/O
26	I/O	I/O	I/O
27	I/O	I/O	I/O
28	GND	GND	GND
29	V _{CCI}	V _{CCI}	V _{CCI}
30	V _{CCA}	V _{CCA}	V _{CCA}
31	I/O	I/O	I/O
32	I/O	I/O	I/O
33	I/O	I/O	I/O
34	I/O	I/O	I/O
35	I/O	I/O	I/O
36	GND	GND	GND
37	I/O	I/O	I/O

144-Pin TQFP			
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function
38	I/O	I/O	I/O
39	I/O	I/O	I/O
40	I/O	I/O	I/O
41	I/O	I/O	I/O
42	I/O	I/O	I/O
43	I/O	I/O	I/O
44	V _{CCI}	V _{CCI}	V _{CCI}
45	I/O	I/O	I/O
46	I/O	I/O	I/O
47	I/O	I/O	I/O
48	I/O	I/O	I/O
49	I/O	I/O	I/O
50	I/O	I/O	I/O
51	I/O	I/O	I/O
52	I/O	I/O	I/O
53	I/O	I/O	I/O
54	PRB, I/O	PRB, I/O	PRB, I/O
55	I/O	I/O	I/O
56	V _{CCA}	V _{CCA}	V _{CCA}
57	GND	GND	GND
58	NC	NC	NC
59	I/O	I/O	I/O
60	HCLK	HCLK	HCLK
61	I/O	I/O	I/O
62	I/O	I/O	I/O
63	I/O	I/O	I/O
64	I/O	I/O	I/O
65	I/O	I/O	I/O
66	I/O	I/O	I/O
67	I/O	I/O	I/O
68	V _{CCI}	V _{CCI}	V _{CCI}
69	I/O	I/O	I/O
70	I/O	I/O	I/O
71	TDO, I/O	TDO, I/O	TDO, I/O
72	I/O	I/O	I/O
73	GND	GND	GND
74	I/O	I/O	I/O

329-Pin PBGA		329-Pin PBGA		329-Pin PBGA		329-Pin PBGA	
Pin Number	A54SX32A Function	Pin Number	A54SX32A Function	Pin Number	A54SX32A Function	Pin Number	A54SX32A Function
A1	GND	AA15	I/O	AC6	I/O	B20	I/O
A2	GND	AA16	I/O	AC7	I/O	B21	I/O
A3	V _{CCI}	AA17	I/O	AC8	I/O	B22	GND
A4	NC	AA18	I/O	AC9	V _{CCI}	B23	V _{CCI}
A5	I/O	AA19	I/O	AC10	I/O	C1	NC
A6	I/O	AA20	TDO, I/O	AC11	I/O	C2	TDI, I/O
A7	V _{CCI}	AA21	V _{CCI}	AC12	I/O	C3	GND
A8	NC	AA22	I/O	AC13	I/O	C4	I/O
A9	I/O	AA23	V _{CCI}	AC14	I/O	C5	I/O
A10	I/O	AB1	I/O	AC15	NC	C6	I/O
A11	I/O	AB2	GND	AC16	I/O	C7	I/O
A12	I/O	AB3	I/O	AC17	I/O	C8	I/O
A13	CLKB	AB4	I/O	AC18	I/O	C9	I/O
A14	I/O	AB5	I/O	AC19	I/O	C10	I/O
A15	I/O	AB6	I/O	AC20	I/O	C11	I/O
A16	I/O	AB7	I/O	AC21	NC	C12	I/O
A17	I/O	AB8	I/O	AC22	V _{CCI}	C13	I/O
A18	I/O	AB9	I/O	AC23	GND	C14	I/O
A19	I/O	AB10	I/O	B1	V _{CCI}	C15	I/O
A20	I/O	AB11	PRB, I/O	B2	GND	C16	I/O
A21	NC	AB12	I/O	B3	I/O	C17	I/O
A22	V _{CCI}	AB13	HCLK	B4	I/O	C18	I/O
A23	GND	AB14	I/O	B5	I/O	C19	I/O
AA1	V _{CCI}	AB15	I/O	B6	I/O	C20	I/O
AA2	I/O	AB16	I/O	B7	I/O	C21	V _{CCI}
AA3	GND	AB17	I/O	B8	I/O	C22	GND
AA4	I/O	AB18	I/O	B9	I/O	C23	NC
AA5	I/O	AB19	I/O	B10	I/O	D1	I/O
AA6	I/O	AB20	I/O	B11	I/O	D2	I/O
AA7	I/O	AB21	I/O	B12	PRA, I/O	D3	I/O
AA8	I/O	AB22	GND	B13	CLKA	D4	TCK, I/O
AA9	I/O	AB23	I/O	B14	I/O	D5	I/O
AA10	I/O	AC1	GND	B15	I/O	D6	I/O
AA11	I/O	AC2	V _{CCI}	B16	I/O	D7	I/O
AA12	I/O	AC3	NC	B17	I/O	D8	I/O
AA13	I/O	AC4	I/O	B18	I/O	D9	I/O
AA14	I/O	AC5	I/O	B19	I/O	D10	I/O

329-Pin PBGA		329-Pin PBGA		329-Pin PBGA		329-Pin PBGA	
Pin Number	A54SX32A Function	Pin Number	A54SX32A Function	Pin Number	A54SX32A Function	Pin Number	A54SX32A Function
D11	V _{CCA}	H1	I/O	L14	GND	P12	GND
D12	NC	H2	I/O	L20	NC	P13	GND
D13	I/O	H3	I/O	L21	I/O	P14	GND
D14	I/O	H4	I/O	L22	I/O	P20	I/O
D15	I/O	H20	V _{CCA}	L23	NC	P21	I/O
D16	I/O	H21	I/O	M1	I/O	P22	I/O
D17	I/O	H22	I/O	M2	I/O	P23	I/O
D18	I/O	H23	I/O	M3	I/O	R1	I/O
D19	I/O	J1	NC	M4	V _{CCA}	R2	I/O
D20	I/O	J2	I/O	M10	GND	R3	I/O
D21	I/O	J3	I/O	M11	GND	R4	I/O
D22	I/O	J4	I/O	M12	GND	R20	I/O
D23	I/O	J20	I/O	M13	GND	R21	I/O
E1	V _{CCI}	J21	I/O	M14	GND	R22	I/O
E2	I/O	J22	I/O	M20	V _{CCA}	R23	I/O
E3	I/O	J23	I/O	M21	I/O	T1	I/O
E4	I/O	K1	I/O	M22	I/O	T2	I/O
E20	I/O	K2	I/O	M23	V _{CCI}	T3	I/O
E21	I/O	K3	I/O	N1	I/O	T4	I/O
E22	I/O	K4	I/O	N2	TRST, I/O	T20	I/O
E23	I/O	K10	GND	N3	I/O	T21	I/O
F1	I/O	K11	GND	N4	I/O	T22	I/O
F2	TMS	K12	GND	N10	GND	T23	I/O
F3	I/O	K13	GND	N11	GND	U1	I/O
F4	I/O	K14	GND	N12	GND	U2	I/O
F20	I/O	K20	I/O	N13	GND	U3	V _{CCA}
F21	I/O	K21	I/O	N14	GND	U4	I/O
F22	I/O	K22	I/O	N20	NC	U20	I/O
F23	I/O	K23	I/O	N21	I/O	U21	V _{CCA}
G1	I/O	L1	I/O	N22	I/O	U22	I/O
G2	I/O	L2	I/O	N23	I/O	U23	I/O
G3	I/O	L3	I/O	P1	I/O	V1	V _{CCI}
G4	I/O	L4	NC	P2	I/O	V2	I/O
G20	I/O	L10	GND	P3	I/O	V3	I/O
G21	I/O	L11	GND	P4	I/O	V4	I/O
G22	I/O	L12	GND	P10	GND	V20	I/O
G23	GND	L13	GND	P11	GND	V21	I/O

144-Pin FBGA			
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function
A1	I/O	I/O	I/O
A2	I/O	I/O	I/O
A3	I/O	I/O	I/O
A4	I/O	I/O	I/O
A5	V _{CCA}	V _{CCA}	V _{CCA}
A6	GND	GND	GND
A7	CLKA	CLKA	CLKA
A8	I/O	I/O	I/O
A9	I/O	I/O	I/O
A10	I/O	I/O	I/O
A11	I/O	I/O	I/O
A12	I/O	I/O	I/O
B1	I/O	I/O	I/O
B2	GND	GND	GND
B3	I/O	I/O	I/O
B4	I/O	I/O	I/O
B5	I/O	I/O	I/O
B6	I/O	I/O	I/O
B7	CLKB	CLKB	CLKB
B8	I/O	I/O	I/O
B9	I/O	I/O	I/O
B10	I/O	I/O	I/O
B11	GND	GND	GND
B12	I/O	I/O	I/O
C1	I/O	I/O	I/O
C2	I/O	I/O	I/O
C3	TCK, I/O	TCK, I/O	TCK, I/O
C4	I/O	I/O	I/O
C5	I/O	I/O	I/O
C6	PRA, I/O	PRA, I/O	PRA, I/O
C7	I/O	I/O	I/O
C8	I/O	I/O	I/O
C9	I/O	I/O	I/O
C10	I/O	I/O	I/O
C11	I/O	I/O	I/O
C12	I/O	I/O	I/O

144-Pin FBGA			
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function
D1	I/O	I/O	I/O
D2	V _{CCI}	V _{CCI}	V _{CCI}
D3	TDI, I/O	TDI, I/O	TDI, I/O
D4	I/O	I/O	I/O
D5	I/O	I/O	I/O
D6	I/O	I/O	I/O
D7	I/O	I/O	I/O
D8	I/O	I/O	I/O
D9	I/O	I/O	I/O
D10	I/O	I/O	I/O
D11	I/O	I/O	I/O
D12	I/O	I/O	I/O
E1	I/O	I/O	I/O
E2	I/O	I/O	I/O
E3	I/O	I/O	I/O
E4	I/O	I/O	I/O
E5	TMS	TMS	TMS
E6	V _{CCI}	V _{CCI}	V _{CCI}
E7	V _{CCI}	V _{CCI}	V _{CCI}
E8	V _{CCI}	V _{CCI}	V _{CCI}
E9	V _{CCA}	V _{CCA}	V _{CCA}
E10	I/O	I/O	I/O
E11	GND	GND	GND
E12	I/O	I/O	I/O
F1	I/O	I/O	I/O
F2	I/O	I/O	I/O
F3	NC	NC	NC
F4	I/O	I/O	I/O
F5	GND	GND	GND
F6	GND	GND	GND
F7	GND	GND	GND
F8	V _{CCI}	V _{CCI}	V _{CCI}
F9	I/O	I/O	I/O
F10	GND	GND	GND
F11	I/O	I/O	I/O
F12	I/O	I/O	I/O

256-Pin FBGA			
Pin Number	A54SX16A Function	A54SX32A Function	A54SX72A Function
P15	I/O	I/O	I/O
P16	I/O	I/O	I/O
R1	I/O	I/O	I/O
R2	GND	GND	GND
R3	I/O	I/O	I/O
R4	NC	I/O	I/O
R5	I/O	I/O	I/O
R6	I/O	I/O	I/O
R7	I/O	I/O	I/O
R8	I/O	I/O	I/O
R9	HCLK	HCLK	HCLK
R10	I/O	I/O	QCLKB
R11	I/O	I/O	I/O
R12	I/O	I/O	I/O
R13	I/O	I/O	I/O
R14	I/O	I/O	I/O
R15	GND	GND	GND
R16	GND	GND	GND
T1	GND	GND	GND
T2	I/O	I/O	I/O
T3	I/O	I/O	I/O
T4	NC	I/O	I/O
T5	I/O	I/O	I/O
T6	I/O	I/O	I/O
T7	I/O	I/O	I/O
T8	I/O	I/O	I/O
T9	V _{CCA}	V _{CCA}	V _{CCA}
T10	I/O	I/O	I/O
T11	I/O	I/O	I/O
T12	NC	I/O	I/O
T13	I/O	I/O	I/O
T14	I/O	I/O	I/O
T15	TDO, I/O	TDO, I/O	TDO, I/O
T16	GND	GND	GND

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
C19	I/O	I/O
C20	V _{CCI}	V _{CCI}
C21	I/O	I/O
C22	I/O	I/O
C23	I/O	I/O
C24	I/O	I/O
C25	NC*	I/O
C26	NC*	I/O
D1	NC*	I/O
D2	TMS	TMS
D3	I/O	I/O
D4	V _{CCI}	V _{CCI}
D5	NC*	I/O
D6	TCK, I/O	TCK, I/O
D7	I/O	I/O
D8	I/O	I/O
D9	I/O	I/O
D10	I/O	I/O
D11	I/O	I/O
D12	I/O	QCLKC
D13	I/O	I/O
D14	I/O	I/O
D15	I/O	I/O
D16	I/O	I/O
D17	I/O	I/O
D18	I/O	I/O
D19	I/O	I/O
D20	I/O	I/O
D21	V _{CCI}	V _{CCI}
D22	GND	GND
D23	I/O	I/O
D24	I/O	I/O
D25	NC*	I/O
D26	NC*	I/O
E1	NC*	I/O

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
E2	NC*	I/O
E3	I/O	I/O
E4	I/O	I/O
E5	GND	GND
E6	TDI, IO	TDI, IO
E7	I/O	I/O
E8	I/O	I/O
E9	I/O	I/O
E10	I/O	I/O
E11	I/O	I/O
E12	I/O	I/O
E13	V _{CCA}	V _{CCA}
E14	CLKB	CLKB
E15	I/O	I/O
E16	I/O	I/O
E17	I/O	I/O
E18	I/O	I/O
E19	I/O	I/O
E20	I/O	I/O
E21	I/O	I/O
E22	I/O	I/O
E23	I/O	I/O
E24	I/O	I/O
E25	V _{CCI}	V _{CCI}
E26	GND	GND
F1	V _{CCI}	V _{CCI}
F2	NC*	I/O
F3	NC*	I/O
F4	I/O	I/O
F5	I/O	I/O
F22	I/O	I/O
F23	I/O	I/O
F24	I/O	I/O
F25	I/O	I/O
F26	NC*	I/O

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
G1	NC*	I/O
G2	NC*	I/O
G3	NC*	I/O
G4	I/O	I/O
G5	I/O	I/O
G22	I/O	I/O
G23	V _{CCA}	V _{CCA}
G24	I/O	I/O
G25	NC*	I/O
G26	NC*	I/O
H1	NC*	I/O
H2	NC*	I/O
H3	I/O	I/O
H4	I/O	I/O
H5	I/O	I/O
H22	I/O	I/O
H23	I/O	I/O
H24	I/O	I/O
H25	NC*	I/O
H26	NC*	I/O
J1	NC*	I/O
J2	NC*	I/O
J3	I/O	I/O
J4	I/O	I/O
J5	I/O	I/O
J22	I/O	I/O
J23	I/O	I/O
J24	I/O	I/O
J25	V _{CCI}	V _{CCI}
J26	NC*	I/O
K1	I/O	I/O
K2	V _{CCI}	V _{CCI}
K3	I/O	I/O
K4	I/O	I/O
K5	V _{CCA}	V _{CCA}

Note: *These pins must be left floating on the A54SX32A device.

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
K10	GND	GND
K11	GND	GND
K12	GND	GND
K13	GND	GND
K14	GND	GND
K15	GND	GND
K16	GND	GND
K17	GND	GND
K22	I/O	I/O
K23	I/O	I/O
K24	NC *	NC
K25	NC *	I/O
K26	NC *	I/O
L1	NC *	I/O
L2	NC *	I/O
L3	I/O	I/O
L4	I/O	I/O
L5	I/O	I/O
L10	GND	GND
L11	GND	GND
L12	GND	GND
L13	GND	GND
L14	GND	GND
L15	GND	GND
L16	GND	GND
L17	GND	GND
L22	I/O	I/O
L23	I/O	I/O
L24	I/O	I/O
L25	I/O	I/O
L26	I/O	I/O
M1	NC *	NC
M2	I/O	I/O
M3	I/O	I/O
M4	I/O	I/O

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
M5	I/O	I/O
M10	GND	GND
M11	GND	GND
M12	GND	GND
M13	GND	GND
M14	GND	GND
M15	GND	GND
M16	GND	GND
M17	GND	GND
M22	I/O	I/O
M23	I/O	I/O
M24	I/O	I/O
M25	NC *	I/O
M26	NC *	I/O
N1	I/O	I/O
N2	V _{CCI}	V _{CCI}
N3	I/O	I/O
N4	I/O	I/O
N5	I/O	I/O
N10	GND	GND
N11	GND	GND
N12	GND	GND
N13	GND	GND
N14	GND	GND
N15	GND	GND
N16	GND	GND
N17	GND	GND
N22	V _{CCA}	V _{CCA}
N23	I/O	I/O
N24	I/O	I/O
N25	I/O	I/O
N26	NC *	NC
P1	NC *	I/O
P2	NC *	I/O
P3	I/O	I/O

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
P4	I/O	I/O
P5	V _{CCA}	V _{CCA}
P10	GND	GND
P11	GND	GND
P12	GND	GND
P13	GND	GND
P14	GND	GND
P15	GND	GND
P16	GND	GND
P17	GND	GND
P22	I/O	I/O
P23	I/O	I/O
P24	V _{CCI}	V _{CCI}
P25	I/O	I/O
P26	I/O	I/O
R1	NC *	I/O
R2	NC *	I/O
R3	I/O	I/O
R4	I/O	I/O
R5	TRST, I/O	TRST, I/O
R10	GND	GND
R11	GND	GND
R12	GND	GND
R13	GND	GND
R14	GND	GND
R15	GND	GND
R16	GND	GND
R17	GND	GND
R22	I/O	I/O
R23	I/O	I/O
R24	I/O	I/O
R25	NC *	I/O
R26	NC *	I/O
T1	NC *	I/O
T2	NC *	I/O

Note: *These pins must be left floating on the A54SX32A device.

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
T3	I/O	I/O
T4	I/O	I/O
T5	I/O	I/O
T10	GND	GND
T11	GND	GND
T12	GND	GND
T13	GND	GND
T14	GND	GND
T15	GND	GND
T16	GND	GND
T17	GND	GND
T22	I/O	I/O
T23	I/O	I/O
T24	I/O	I/O
T25	NC *	I/O
T26	NC *	I/O
U1	I/O	I/O
U2	V _{CCI}	V _{CCI}
U3	I/O	I/O
U4	I/O	I/O
U5	I/O	I/O
U10	GND	GND
U11	GND	GND
U12	GND	GND
U13	GND	GND
U14	GND	GND
U15	GND	GND
U16	GND	GND
U17	GND	GND
U22	I/O	I/O
U23	I/O	I/O
U24	I/O	I/O
U25	V _{CCI}	V _{CCI}
U26	I/O	I/O
V1	NC *	I/O

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
V2	NC *	I/O
V3	I/O	I/O
V4	I/O	I/O
V5	I/O	I/O
V22	V _{CCA}	V _{CCA}
V23	I/O	I/O
V24	I/O	I/O
V25	NC *	I/O
V26	NC *	I/O
W1	I/O	I/O
W2	I/O	I/O
W3	I/O	I/O
W4	I/O	I/O
W5	I/O	I/O
W22	I/O	I/O
W23	V _{CCA}	V _{CCA}
W24	I/O	I/O
W25	NC *	I/O
W26	NC *	I/O
Y1	NC *	I/O
Y2	NC *	I/O
Y3	I/O	I/O
Y4	I/O	I/O
Y5	NC *	I/O
Y22	I/O	I/O
Y23	I/O	I/O
Y24	V _{CCI}	V _{CCI}
Y25	I/O	I/O
Y26	I/O	I/O

Note: *These pins must be left floating on the A54SX32A device.

Datasheet Categories

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